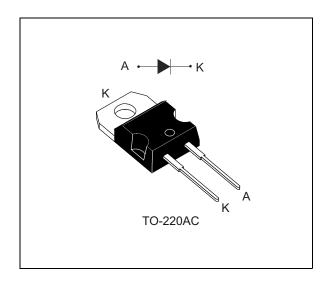


STPSC10C065D-L

650 V power Schottky silicon carbide diode

Datasheet - production data



Features

- No or negligible reverse recovery
- Switching behavior independent of temperature
- · High forward surge capability

Description

The SiC diode is an ultrahigh performance power Schottky diode. It is manufactured using a silicon carbide substrate. The wide band gap material allows the design of a Schottky diode structure with a 650 V rating. Due to the Schottky construction, no recovery is shown at turn-off and ringing patterns are negligible. The minimal capacitive turn-off behavior is independent of temperature.

Especially suited for use in PFC applications, ST SiC diode will boost the performance in hard switching conditions. Its high forward surge capability ensures more margin during transient phases.

Table 1. Device summary

Symbol	Value
I _{F(AV)}	10 A
V _{RRM}	650 V
T _j (max)	175 °C

This is information on a product in full production.

Characteristics STPSC10C065D-L

1 Characteristics

Table 2. Absolute ratings (limiting values at 25 °C unless otherwise specified)

Symbol	Par	Value	Unit	
V_{RRM}	Repetitive peak reverse voltage		650	V
I _{F(RMS)}	Forward rms current		22	Α
I _{F(AV)}	Average forward current	$T_{c} = 120 {}^{\circ}C^{(1)}, DC$	10	Α
	Surge non repetitive forward current	t _p = 10 ms sinusoidal, T _c = 25 °C	85	
I _{FSM}		$t_p = 10 \text{ ms sinusoidal}, T_c = 125 °C$	75	Α
		$t_p = 10 \mu s \text{ square}, T_c = 25 \text{ °C}$	500	
I _{FRM}	Repetitive peak forward current	$T_c = 120 {}^{\circ}C^{(1)}, T_j = 175 {}^{\circ}C, \delta = 0.1$	42	Α
T _{stg}	Storage temperature range		-55 to +175	°C
Tj	Operating junction temperature ⁽²⁾		-40 to +175	°C

^{1.} Value based on $R_{th(j-c)}$ (max)

Table 3. Thermal resistance

Symbol	Parameter	Val	Unit	
Symbol	raiametei	Тур.	Max.	Onic
R _{th(j-c)}	Junction to case	1.3	2.0	°C/W

Table 4. Static electrical characteristics

Symbol	Parameter	Tests conditions		Min.	Тур.	Max.	Unit
(1)	I _R ⁽¹⁾ Reverse leakage current	T _j = 25 °C	$V_R = V_{RRM}$	-	9	100	μΑ
'R`		T _j = 150 °C		1	85	425	
V_ (2)	V _F ⁽²⁾ Forward voltage drop	T _j = 25 °C	I _F = 10 A	-	1.56	1.75	V
VF		T _j = 150 °C		-	1.98	2.5	

^{1.} $t_p = 10 \text{ ms}, \delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 1.35 \text{ x I}_{F(AV)} + 0.12 \text{ x I}_{F^2(RMS)}$$

Table 5. Dynamic electrical characteristics

Symbol	Parameter	Test conditions	Тур.	Unit
Q _{cj} ⁽¹⁾	Total capacitive charge	V _R = 400 V	26.4	nC
C _j Total capacitance	$V_R = 0 \text{ V}, T_C = 25 \text{ °C}, F = 1 \text{ MHz}$	480	pF	
	$V_R = 300 \text{ V}, T_C = 25 \text{ °C}, F = 1 \text{ MHz}$	47	рΓ	

^{1.} Most accurate value for the capacitive charge: $Q_{Cj} = \int_0^{v_{Out}} c_j(V_R) . dV_R$

577

^{2.} $\frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$ condition to avoid thermal runaway for a diode on its own heatsink

^{2.} $t_p = 500 \ \mu s, \ \delta < 2\%$

STPSC10C065D-L Characteristics

Figure 1. Forward voltage drop versus forward current (typical values, low level)

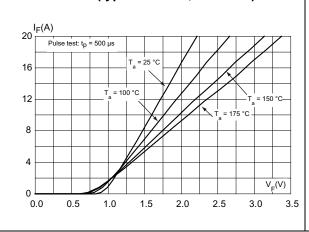


Figure 2. Forward voltage drop versus forward current (typical values, high level)

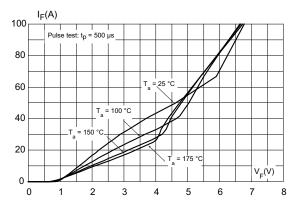


Figure 3. Reverse leakage current versus reverse voltage applied (typical values)

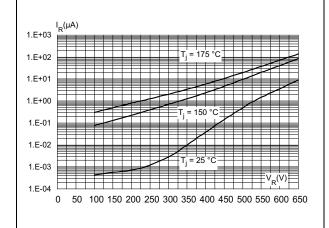


Figure 4. Peak forward current versus case temperature

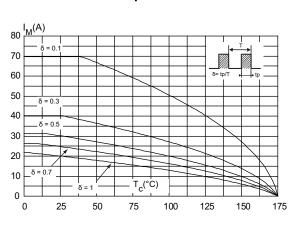


Figure 5. Junction capacitance versus reverse voltage applied (typical values)

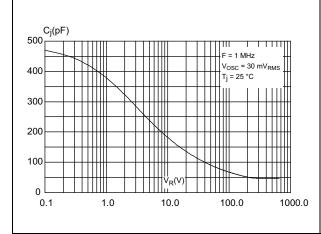
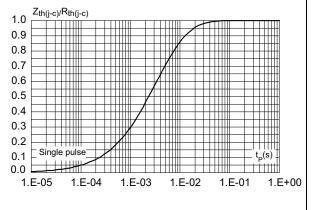


Figure 6. Relative variation of thermal impedance junction to case versus pulse duration





Characteristics STPSC10C065D-L

1.E-03

1.E-02

1.E-04

1.E+01

1.E-05

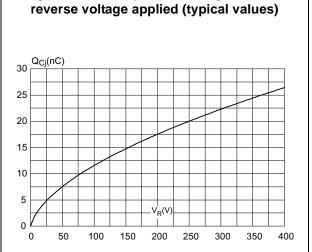


Figure 8. Total capacitive charges versus

577

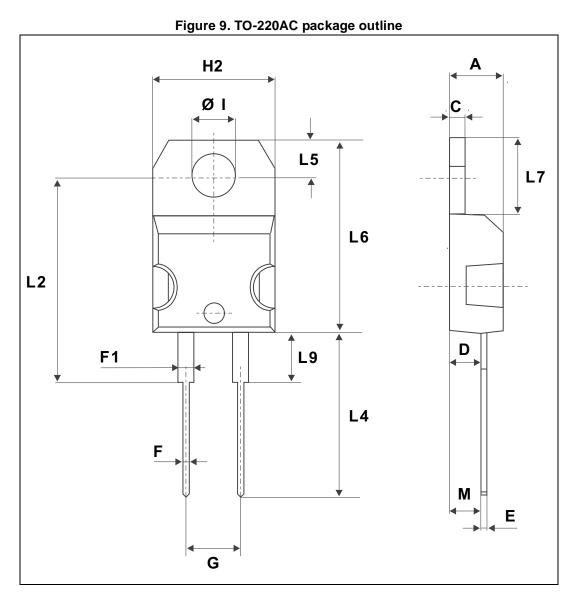
4/8 DocID027788 Rev 1

2 Package information

- Epoxy meets UL94, V0
- Recommended torque value (TO-220AC): 0.55 N·m
- Maximum torque value: 0.7 N⋅m for TO-220AC
- Cooling method: conduction (C)

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

2.1 TO-220AC package information



577

DocID027788 Rev 1

Package information STPSC10C065D-L

Table 6. TO-220AC package mechanical data

	Dimensions				
Ref.	Millimeters		Inches		
	Min. Max.		Min.	Max.	
А	4.40	4.60	0.173	0.181	
С	1.23	1.32	0.048	0.051	
D	2.40	2.72	0.094	0.107	
Е	0.49	0.70	0.019	0.027	
F	0.61	0.88	0.024 0.034		
F1	1.14	1.70	0.044	0.066	
G	4.95	5.15	0.194 0.202		
H2	10.00	10.40	0.393 0.409		
L2	16.40 typ.		0.645 typ.		
L4	13.00	14.00	0.511	0.551	
L5	2.65	2.95	0.104	0.116	
L6	15.25	15.75	0.600 0.620		
L7	6.20	6.60	0.244	0.259	
L9	3.50	3.93	0.137	0.154	
М	2.6 typ.		0.102	typ.	
Diam. I	3.75	3.85 0.147 0.15		0.151	

3 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPSC10C065D-L	PSC10C065D	TO-220AC	1.86 g	50	Tube

4 Revision history

Table 8. Document revision history

Date	Revision	Changes
18-May-2015	1	First issue.



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57

8/8 DocID027788 Rev 1